

- 221 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1
- 222 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- 223 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- 224 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.

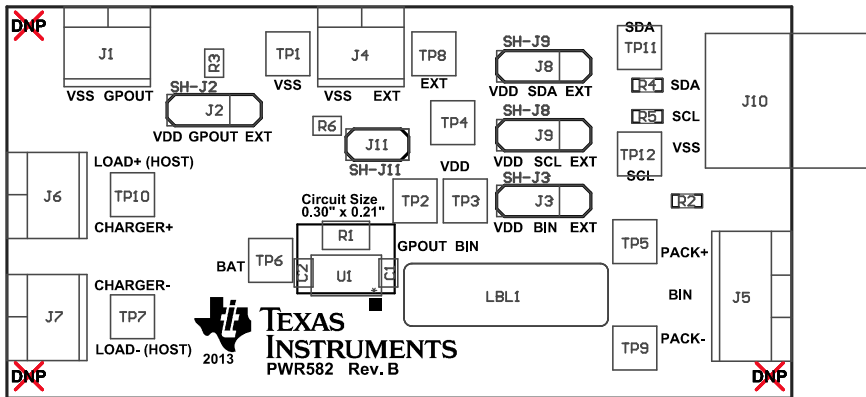


TABLE 1

Variant	Label text
001	bq27441EUM-G1A
002	bq27441EUM-G1B

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PWR582	REV: B	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 10/1/2013	1:14:55 PM	TEXAS INSTRUMENTS

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